

IN THE CLAIMS:

Please amend the claims as follows.

Claim 1 (Currently Amended): A back-illuminated semiconductor device comprising:
a semiconductor substrate, having:

a photodetecting unit formed on one surface,

a thinned portion formed by etching a region, opposing the photodetecting unit, of
another surface,

an outer edge surrounding the thinned portion, and

first electrodes disposed on the one surface at the outer edge and electrically
connected to the photodetecting unit;

a wiring substrate, disposed to oppose the one surface side of the semiconductor substrate
and having second electrodes connected via conductive bumps to the first electrodes; and

a resin, filling a gap between the wiring substrate and the outer edge with the conductive
bumps; and

wherein the resin is a resin sheet, and

wherein a communicating portion is formed so as to laterally penetrate through the resin
sheet,

wherein the first and second electrodes surround a space between the wiring substrate and
the thinned portion of the semiconductor,

wherein the resin sheet surrounds said space, and

wherein the communicating portion penetrating the resin sheet is configured to allow air
communication in it.

Claims 2-3 (Canceled).

Claim 4 (New): The semiconductor device according to Claim 1,
wherein the resin sheet has four corners,
wherein there are other communicating portions laterally penetrating the resin sheet, and
wherein the communicating portions are respectively arranged at the four corners of the
resin sheet.

Claim 5 (New): The semiconductor device according to Claim 1,
wherein the communicating portion is not sealed.

Claim 6 (New): The semiconductor device according to Claim 1, further comprising:
a plurality of chip resistors disposed on a region of the wiring substrate, wherein the
region on which the plurality of chip resistors are disposed opposes the thinned portion.

Claim 7 (New): The semiconductor device according to Claim 6,
wherein the plurality of chip resistors are aligned one-dimensionally.